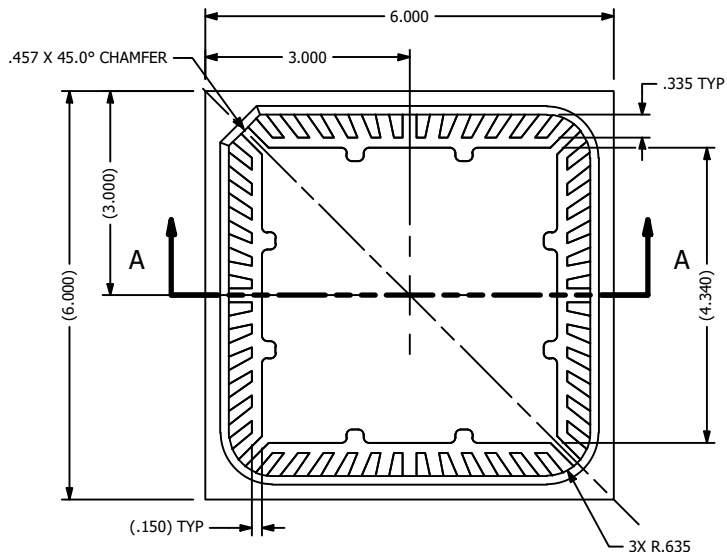
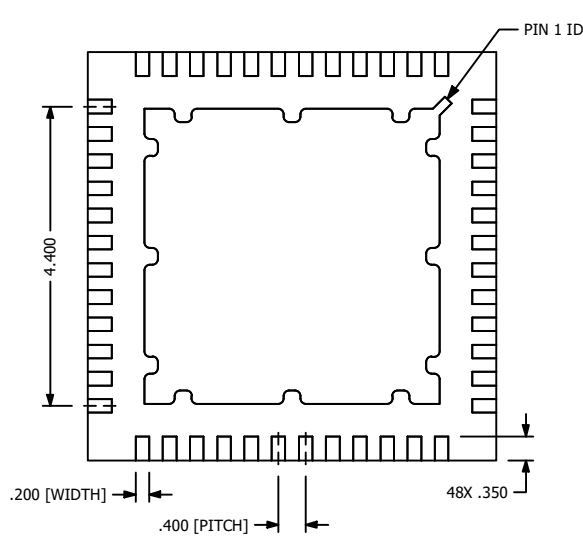
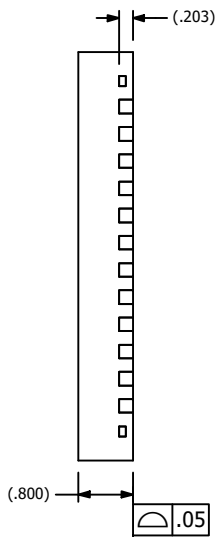


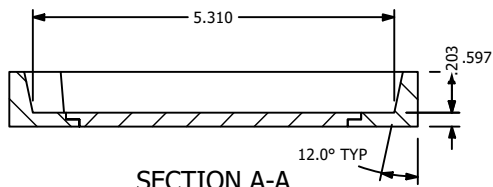
REVISION HISTORY				
ECN	REV	DESCRIPTION	DATE	APRVD
12069	1	INITIAL RELEASE	5/10/2023	BAF



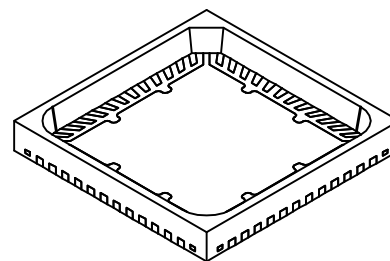
TOP VIEW



BOTTOM VIEW



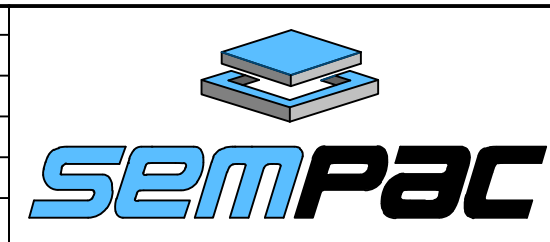
SECTION A-A



NOTES:

- MATERIAL:
  - BODY: PLASTIC, SEMICONDUCTOR GRADE
  - LEADFRAME: COPPER, 194 FH, 0.203± 0.008 THICK
- PLATING: MIL-G-45204C / TYPE III Au, GRADE A, 35µin[0.889µm] OVER QQ-N-290 / CLASS 1. 15 - 30µin[0.381 - 0.762µm] SULFAMATE NI
- GEOMETRY:
  - DIE PAD: 4.340mm X 4.340mm
  - BODY TO FRAME OFFSET IS 0.076mm MAX
- PACKAGE CONFORMS TO JEDEC: MO-220

THE INFORMATION AND DESIGNS CONTAINED IN THIS DRAWING ARE CONFIDENTIAL AND THE SOLE PROPRIETARY PROPERTY OF SEMPAK INC. NEITHER THIS DESIGN NOR ANY INFORMATION CONTAINED HEREIN MAY BE REPRODUCED OR DISCLOSED TO OTHERS WITHOUT THE EXPRESSED, WRITTEN CONSENT OF SEMPAK INC.	NAME	DATE
	DRAWN ZAM	5/9/2023
	CHECKED XDH	5/9/2023
	ENG APPR BAF	5/9/2023
DOC CNTL		
UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS.	THIRD ANGLE PROJECTION	
TOLERANCES: XX = ±0.25 XXX = ±0.125 ANGLES = ±0.5°		



TITLE **48 LEAD 6mm X 6mm MLP OPEN-PAK**

SIZE A	SCALE DNS	SHEET 1 OF 1	REV 1	PRODUCT MLP6X6-48-OP-01	PN 10256
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